

REWORKABLE EDGE BOND ADHESIVE

UA-2605-BT2 is a reworkable edgebond adhesive for BGA's, CSP's, and other surface mount components. The adhesive enhances drop and bend test performance as well as improves resistance against shock and vibration. The adhesive cures quickly at low temperature and exhibits excellent adhesion to organic substrates.

TYPICAL PROPERTIES

Color	Black
Filler Content, %	50
Viscosity, 25°C	
SSA #14, 1 rpm, cps	635,000
Cure Conditions, minutes	
130°C	10
140°C	5
150°C	1
Specific Gravity (g/cc)	1.56
Shelf Life @ -5°C, months	12
Pot Life @ 25°C, days	14

CURED PROPERTIES

CTE1, ppm/°C	30
CTE2, ppm/°C	102
Tg, °C (TMA)	130
Hardness (Shore D)	93
Storage Modulus, GPa (DMA)	7.3
Dielectric Constant (Dk), 10GHz	3.3
Dissipation Factor (Df), 10GHz	0.022
Volatiles Content, wt% loss on cure	<2.0
Outgassing per ASTM E-595, cured 10 minute, 130°C	
Total Mass loss (TLM%)	0.44
Collected Volatile Condensable Material (%CVCM)	0.01

DIRECTIONS FOR USE

Dispense adhesive along the perimeter of the assembled component. Leave a small edge section unbonded so as not to completely seal the air under the chip. This is to ensure that there is an outlet for any expansion of the air during processing. **DO NOT LEAVE ANY OF THE CORNERS UNBONDED.** Cure according to the listed cure schedules. Recommended cure temperature is actual temperature of the adhesive. For other cure temperatures, consult your Zymet sales representative.

DIRECTIONS FOR REWORK

Remove adhesive from the component at >180°C with an orange stick. Alternatively, scrap adhesive away using a chisel tipped soldering iron. For more detailed instructions, contact your Zymet sales representative.

STORAGE AND HANDLING

Store at -5°C, or below. Use good industrial hygiene to avoid skin and eye contact. Wash off affected area with soap and water.

Refer to SDS before use or disposal.

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